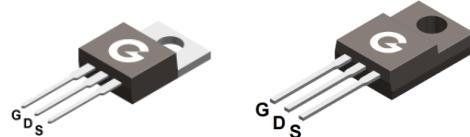
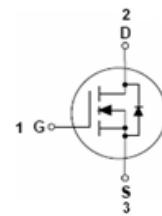


### Features

- Low  $R_{DS(ON)}$
- Fast switching
- Low gate charge
- Low Reverse transfer capacitances

**HF**



### Mechanical Data

- Case: TO-220AB, ITO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matted-Tin plated; Solderable Per MIL-STD-202, Method 208

**TO-220AB**

**ITO-220AB**

### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL10N70	TO-220AB	50 pcs / Tube	10N70
BL10N70F	ITO-220AB	50 pcs / Tube	10N70F

### Maximum Ratings (@ $T_c = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	700	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current ( $T_c = 25^\circ\text{C}$ )	$I_D$	10	A
Continuous Drain Current ( $T_c = 100^\circ\text{C}$ )		6.3	A
Pulsed Drain Current ( $t_p = 10\mu\text{s}$ , $T_c = 25^\circ\text{C}$ )	$I_{DM}$	40	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	380	mJ
Power Dissipation (TO-220AB, $T_c = 25^\circ\text{C}$ )	$P_D$	125	W
Power Dissipation (ITO-220AB, $T_c = 25^\circ\text{C}$ )		40	W
Operating Junction Temperature Range	$T_J$	-55 ~ +150	°C
Storage Temperature Range	$T_{STG}$	-55 ~ +150	°C

### Thermal Characteristics

Parameter	Symbol	TO-220AB	ITO-220AB	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	1	3.1	°C/W
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	50	62.5	°C/W

**Electrical Characteristics** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}$ , $I_D = 250\mu\text{A}$	700	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 700\text{V}$ , $V_{GS} = 0\text{V}$	-	-	10	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 30\text{V}$ , $V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$R_{DS(ON)}$	Drain-Source On-resistance *1	$V_{GS} = 10\text{V}$ , $I_D = 5\text{A}$	-	-	1.1	$\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\mu\text{A}$	2	-	4	V
<b>Dynamic Characteristics</b>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0\text{V}$ $V_{DS} = 25\text{V}$ $f = 1\text{MHz}$	-	1563	-	pF
$C_{OSS}$	Output Capacitance		-	120	-	
$C_{RSS}$	Reverse Transfer Capacitance		-	6.2	-	
<b>Switching Characteristics</b>						
$t_{d(ON)}$	Turn-on Delay Time *3	$V_{DD} = 350\text{V}$ $V_{GS} = 15\text{V}$ $I_D = 10\text{A}$ $R_G = 10\Omega$	-	25.6	-	ns
$t_r$	Turn-on Rise Time *3		-	24.8	-	
$t_{d(OFF)}$	Turn-Off Delay Time *3		-	48.2	-	
$t_f$	Turn-Off Fall Time *3		-	30.4	-	
$Q_G$	Total Gate-Charge	$V_{DD} = 560\text{V}$ $V_{GS} = 10\text{V}$ $I_D = 10\text{A}$	-	34	-	nC
$Q_{GS}$	Gate to Source Charge		-	7.2	-	
$Q_{GD}$	Gate to Drain (Miller) Charge		-	15.2	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage *1	$I_{SD} = 10\text{A}$ , $V_{GS} = 0\text{V}$	-	-	1.5	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 10\text{A}$ , $V_{GS} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$	-	504	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	3.9	-	$\mu\text{C}$

Notes:

- The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- The  $E_{AS}$  data shows Max. rating. The test condition is  $V_{DD} = 100\text{V}$ ,  $V_{GS} = 15\text{V}$ ,  $L = 50\text{mH}$
- Guaranteed by design, not subject to production

### Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

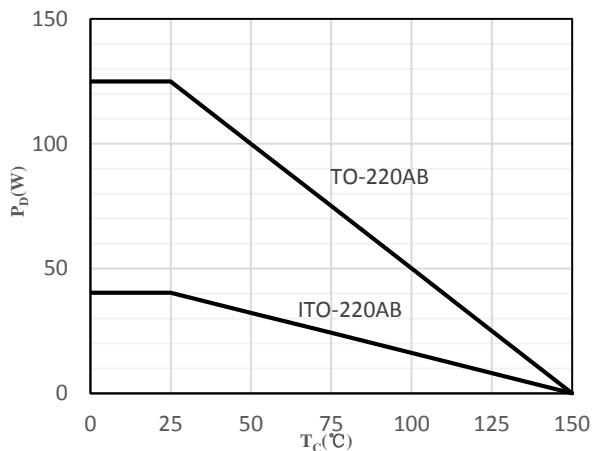


Fig 1 Power Dissipation

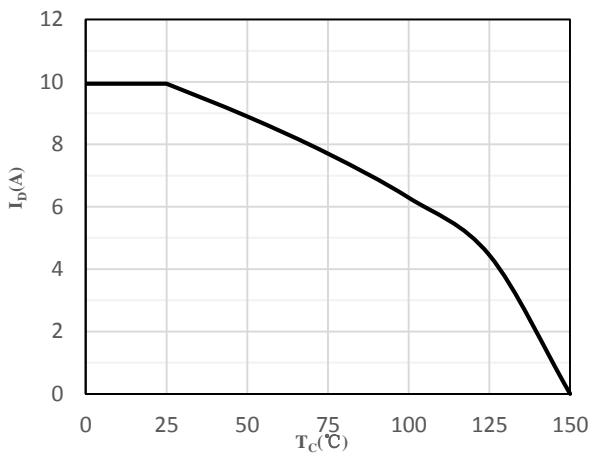


Fig 2 Drain Current

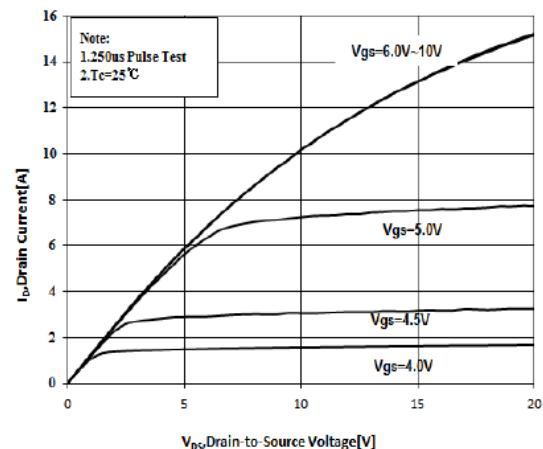


Fig 3 Typical Output Characteristics

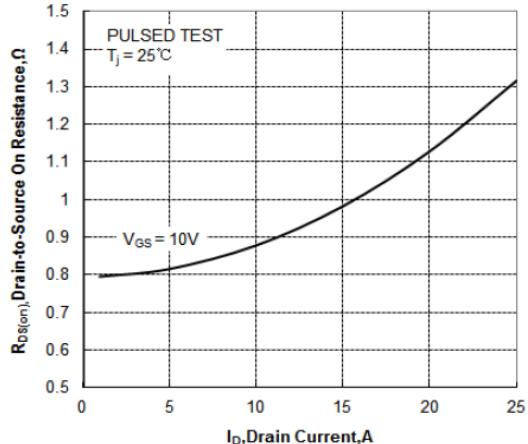


Fig 4 On-Resistance vs. Drain Current  
and Gate Voltage

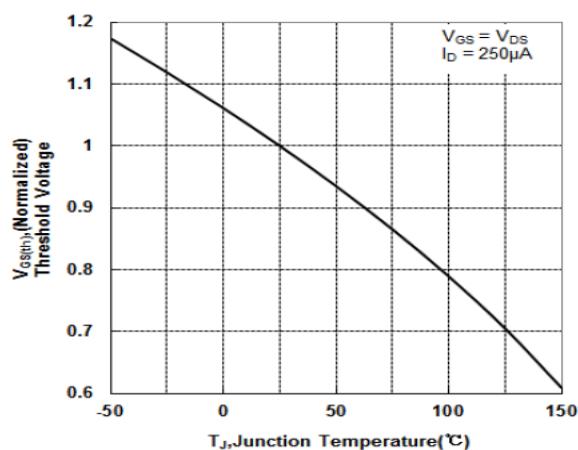


Fig 5 Normalized  $V_{GS(th)}$  vs. Junction Temperature

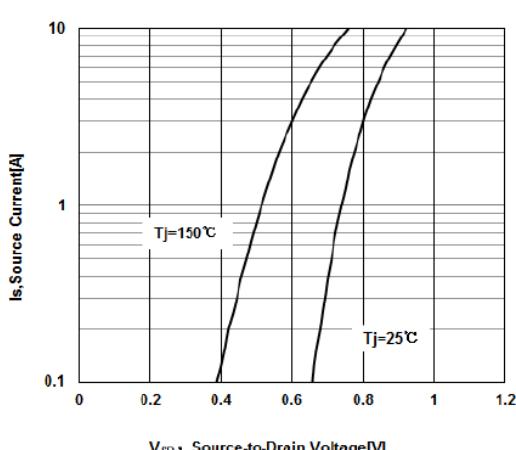


Fig 6 Body-Diode Characteristics

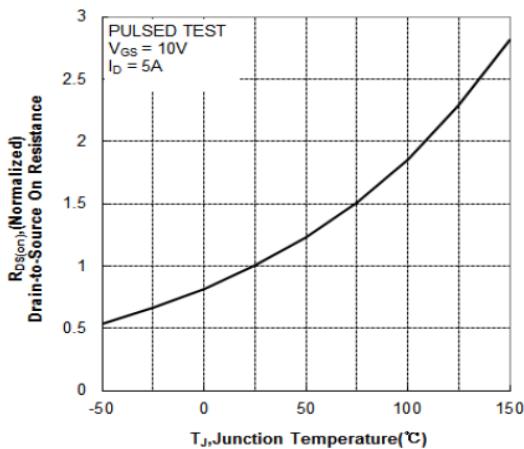


Fig 7 Normalized On-Resistance vs. Junction Temperature

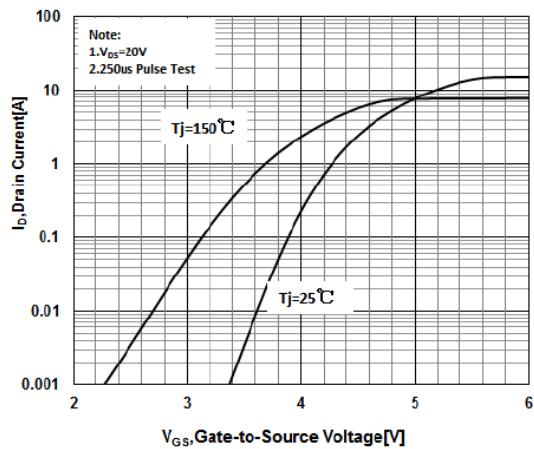


Fig 8 Transfer Characteristics

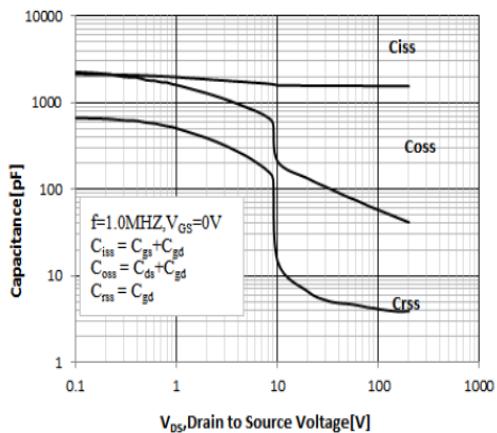


Fig 9 Capacitance Characteristics

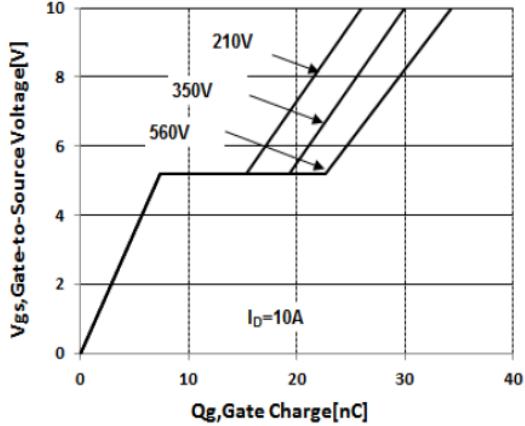


Fig 10 Gate-Charge Characteristics

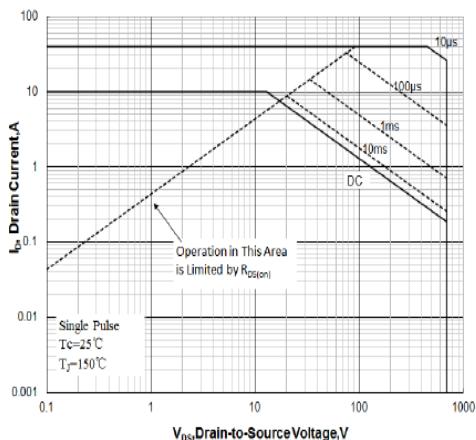


Fig 11 Safe Operation Area (TO-220AB)

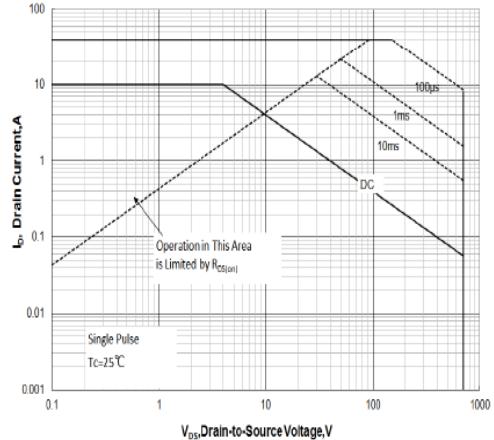
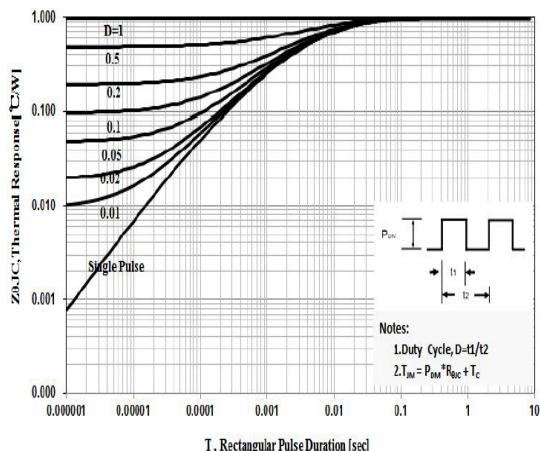
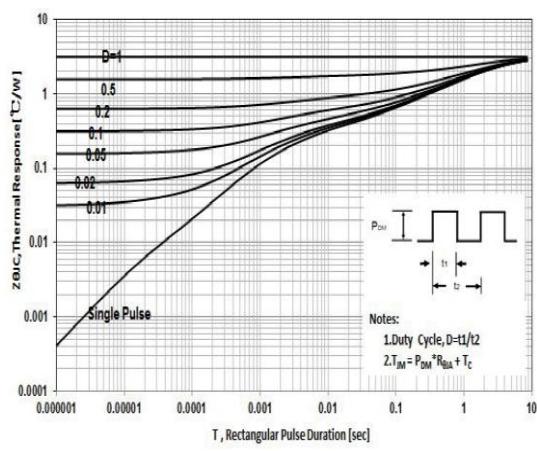


Fig 12 Safe Operation Area (ITO-220AB)

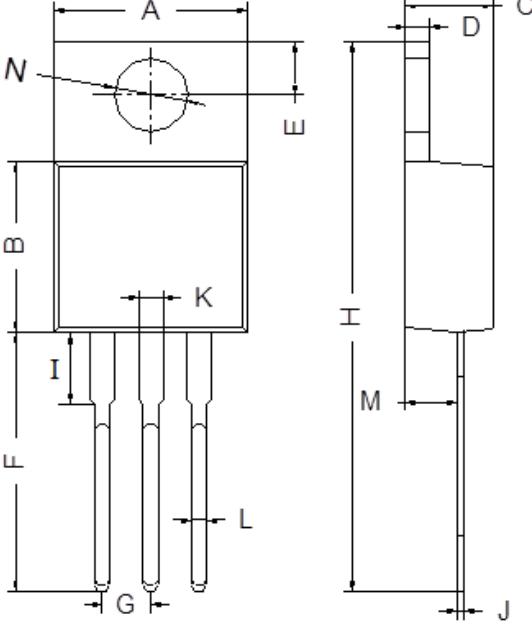


**Fig 13 Maximum transient thermal impedance  
(TO-220AB)**



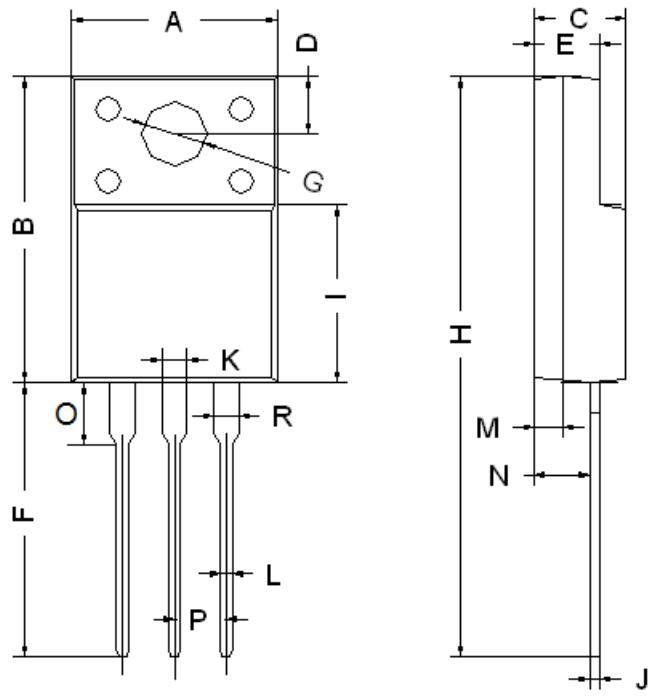
**Fig 14 Maximum transient thermal impedance  
(ITO-220AB)**

### Package Outline Dimensions (Unit: mm)



<b>TO-220AB</b>		
Dimension	Min.	Max.
A	9.80	10.30
B	8.70	9.10
C	4.37	4.77
D	1.07	1.47
E	2.64	2.84
F	13.14	13.74
G	2.44	2.64
H	28.03	28.83
I	3.50	4.00
J	0.28	0.48
K	1.22	1.32
L	0.71	0.91
M	2.40	2.60
N	3.76	3.96



<b>ITO-220AB</b>		
Dimension	Min.	Max.
A	9.90	10.30
B	14.80	15.20
C	4.30	4.70
D	2.50	2.90
E	2.80	3.30
F	13.00	13.60
G	3.10	3.30
H	28.00	28.60
I	7.90	8.90
J	0.40	0.60
L	0.70	0.90
M	1.30	1.50
N	2.60	2.80
O	2.60	3.10
P	2.45	2.65
K/R	1.10	1.30

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